

Multilayer Power Inductor

CIG22L Series (2520/ EIA 1008)

APPLICATION

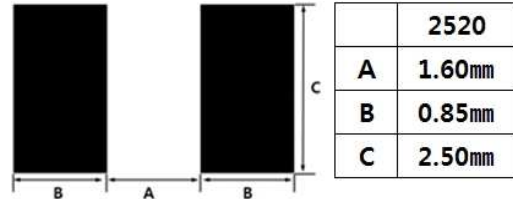
Mobile phones, DSC, DVC, PDA etc. for DC-DC Converter

FEATURES

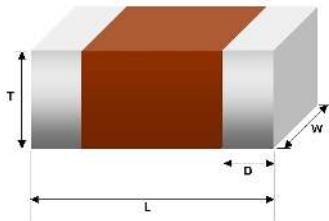
- Low DC resistance
- Magnetically shielded structure
- Free of all RoHS-regulated substances
- Monolithic structure for high reliability



RECOMMENDED LAND PATTERN



DIMENSION



| TYPE | Dimension [mm] | | | |
|------|----------------|---------|---------|-----------|
| | L | W | T | D |
| 22 | 2.5±0.2 | 2.0±0.2 | 0.9±0.1 | 0.55±0.25 |

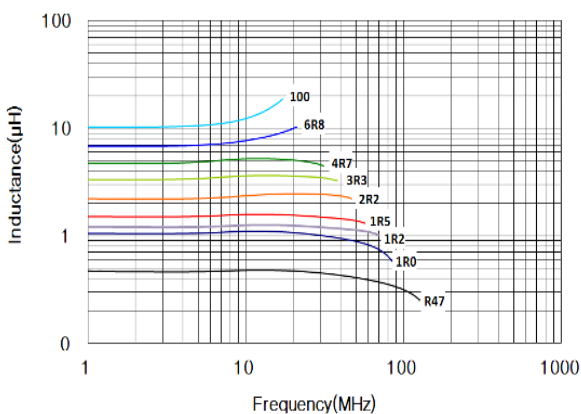
DESCRIPTION

| Part no. | Size (inch/mm) | Inductance (uH)@1MHz | DC Resistance(Ω) | Rated Current (A) Max. |
|--------------|----------------|----------------------|------------------|------------------------|
| CIG22LR47MNE | 1008/2520 | 0.47 ±20 % | 0.040 ±25 % | 1.80 |
| CIG22L1R0MNE | 1008/2520 | 1.0 ±20 % | 0.060 ±25 % | 1.60 |
| CIG22L1R2MNE | 1008/2520 | 1.2 ±20 % | 0.065 ±25 % | 1.50 |
| CIG22L1R5MNE | 1008/2520 | 1.5 ±20 % | 0.070 ±25 % | 1.50 |
| CIG22L2R2MNE | 1008/2520 | 2.2 ±20 % | 0.080 ±25 % | 1.30 |
| CIG22L3R3MNE | 1008/2520 | 3.3 ±20 % | 0.100 ±25 % | 1.20 |
| CIG22L4R7MNE | 1008/2520 | 4.7 ±20 % | 0.110 ±25 % | 1.10 |
| CIG22L6R8MNE | 1008/2520 | 6.8 ±20 % | 0.203 ±30 % | 0.80 |
| CIG22L100MNE | 1008/2520 | 10.0 ±20 % | 0.323 ±30 % | 0.60 |

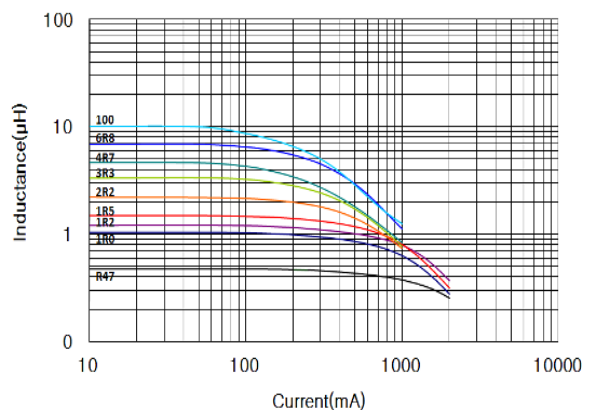
※ Rated Current (A): DC current value when the self-generation of heat rises to 40°C (Reference ambient temperature:25°C)
 ※ Operating temperature range: -40 to +125°C (Including self-temperature rise)
 ※ Test equipment: Agilent :E4991A+16092A

CHARACTERISTIC DATA

1) Frequency characteristics (Typ.)



2) DC Bias characteristics (Typ.)



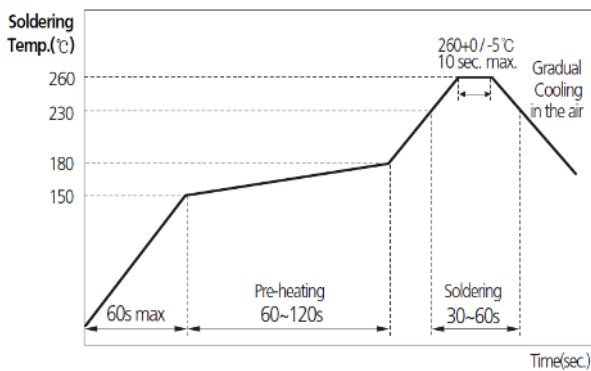
PRODUCT IDENTIFICATION

CI G 22 L 1R0 M N E
(1) (2) (3) (4) (5) (6) (7) (8)

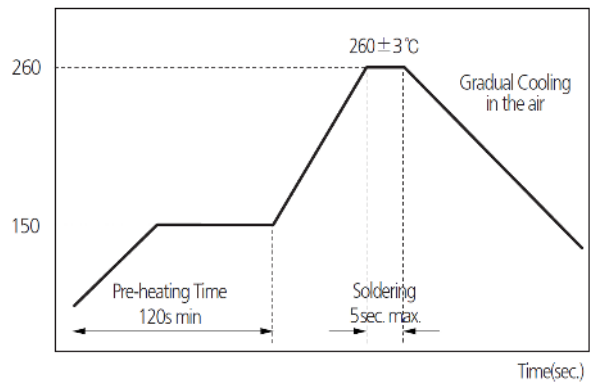
- (1) Chip Inductor
- (2) Power Inductor
- (3) Dimension
- (4) Product Series (L: Low Rdc)
- (5) Inductance (1R0:1.0uH)
- (6) Tolerance (M:±20%)
- (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (8) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

| Packaging Style | Quantity(pcs/reel) |
|-----------------|--------------------|
| Embossed Taping | 3,000 |

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